The 46th International Spring Seminar On Electronics Technology

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”Revolutionizing the Electronics Ecosystems – Chiplet and Heterogeneous Integration”

Keynote speaker:

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Title of the presentation:

Improved chip bonding solutions with sinter technology

Short CV:
Istvan Molnar’s career has started in 2005 as a Cad Engineer. In 2008, he was hired by MacDermid Alpha and have been working there ever since. Started as a cad engineer in the stencil production, than as a supervisor of the department, responsible for the Eastern European region. His connection to the power applications including the sinter technology was started in 2015. At first from the production side then as a technical support responsible for the Eastern European region. Since 2023, his scope of duties have been expanded with microelectronics and sensor business, as an European technical lead.

Abstract: The shift towards high-reliability products and processes can be clearly observed in the entire electronics industry. It is a complex challenge to meet the ever-increasing customer and market expectations, such as higher power density, higher thermal conductivity, and lower weight. The wide range of sinter solutions can be a perfect answer to these high expectations, for which MacDermid Alpha offers state of the art materials and solutions.

In the first part of the presentation, after showing the path to the current stage, a simple example will be used to explain where the critical points might be in the chip bonding and a possible sinter solutions.

In the second part, some insight will be given to the basics of the sinter technology.

Finally, the presentation will be closed with some application solutions, which can provide a reference point for the practical sinter implementation.